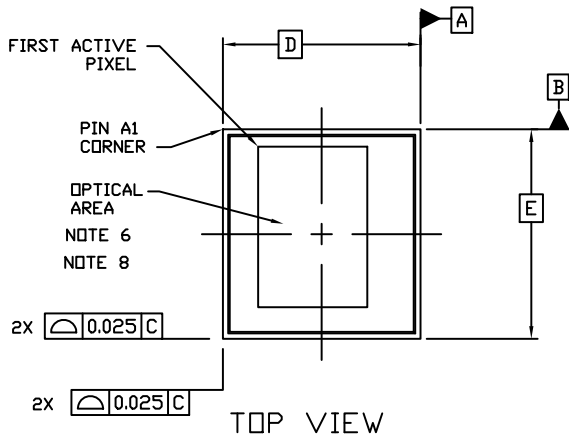


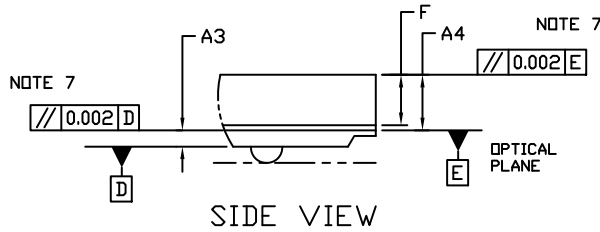
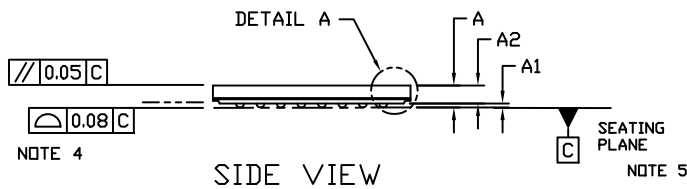
**ODCSP64 6.278x6.648
CASE 570BH
ISSUE A**

DATE 31 MAY 2018

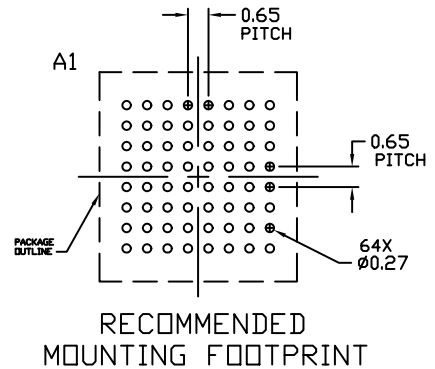
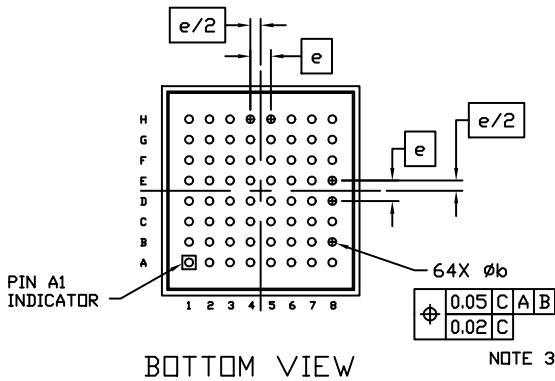


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. MAXIMUM ROTATION OF OPTICAL AREA RELATIVE TO D AND E WILL BE 0.5°. OPTICAL AREA IS DEFINED BY THE ACTIVE PIXEL ARRAY. REFER TO THE DEVICE DATASHEET FOR TOTAL ARRAY AND FIRST ACTIVE PIXEL DEFINITIONS.
7. PARALLELISM APPLIES ONLY TO THE OPTICAL AREA.
8. OPTICAL CENTER OFFSET WITH RESPECT TO THE PACKAGE CENTER IS X=-290 MICRONS, Y=229.8 MICRONS ±75 MICRONS.



DIM	MILLIMETERS	
	MIN.	MAX.
A	---	0.81
A1	0.10	0.16
A2	0.57	REF
A3	0.104	0.154
A4	0.421	0.461
b	0.22	0.28
D	6.278	BSC
E	6.648	BSC
e	0.65	BSC
F	0.38	0.42



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